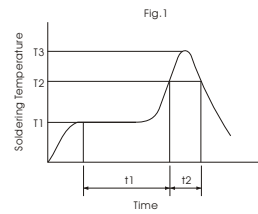




SOLDERING and MOUNTING RECOMMENDATIONS

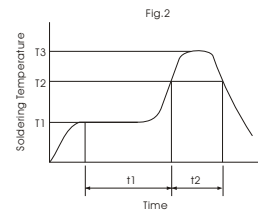
1. Conditions for Terminal Soldering by reflow soldering method

a. In case of Infrared Soldering



T1: +120to+150°C(+248to+302°F)  
 T1: +180to+200°C(+356to+392°F)  
 T1: +245°C(+473°F)Max.  
 T2: +30Sec.Max.

b. In case of Vapor Phase Soldering



T1: +120to+150°C(+248to+302°F)  
 T1: +180to+200°C(+356to+392°F)  
 T1: +215°C(+419°F)Max.  
 T1: +40to 60Sec  
 T2: +60Sec.Max.

2. Usage of Stand-Off A & B in Base Area

The Stand-Offs shown in the Fig. 3 are designed to Anchor Relays temporarily to PC Board with glue before Terminal Soldering.

